



Material Content Data Sheet



Sales Product Name		BSC0910NDI		Issued		4. July 2019		
MA#		MA001092620						
Package		PG-TISON-8-3		Weight*		101.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.848	0.83	0.83	8331	8331
chip_2	inorganic material	silicon	7440-21-3	0.210	0.21	0.21	2067	2067
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		101	
	non noble metal	zinc	7440-66-6	0.041	0.04		403	
	non noble metal	iron	7439-89-6	0.822	0.81		8069	
wire	non noble metal	copper	7440-50-8	33.360	32.76	33.62	327643	336216
	noble metal	gold	7440-57-5	0.068	0.07	0.07	671	671
	organic material	carbon black	1333-86-4	0.092	0.09		901	
encapsulation	plastics	epoxy resin	-	4.724	4.64		46394	
	inorganic material	silicondioxide	60676-86-0	41.047	40.31	45.04	403133	450428
leadfinish	non noble metal	tin	7440-31-5	1.108	1.09	1.09	10882	10882
plating	noble metal	silver	7440-22-4	0.186	0.18	0.18	1825	1825
solder	non noble metal	tin	7440-31-5	0.032	0.03		319	
	noble metal	silver	7440-22-4	0.041	0.04		399	
	non noble metal	lead	7439-92-1	1.551	1.52	1.59	15233	15951
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.01		52	
	non noble metal	zinc	7440-66-6	0.021	0.02		208	
	non noble metal	iron	7439-89-6	0.424	0.42		4167	
	non noble metal	copper	7440-50-8	17.228	16.92	17.37	169202	173629
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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